LPNHE-FBK thin n-on-p pixel sensors for HL-LHC upgrade and beyond

VERTEX 2020 – 29th International Workshop on Vertex Detectors,
October 5-8, 2020

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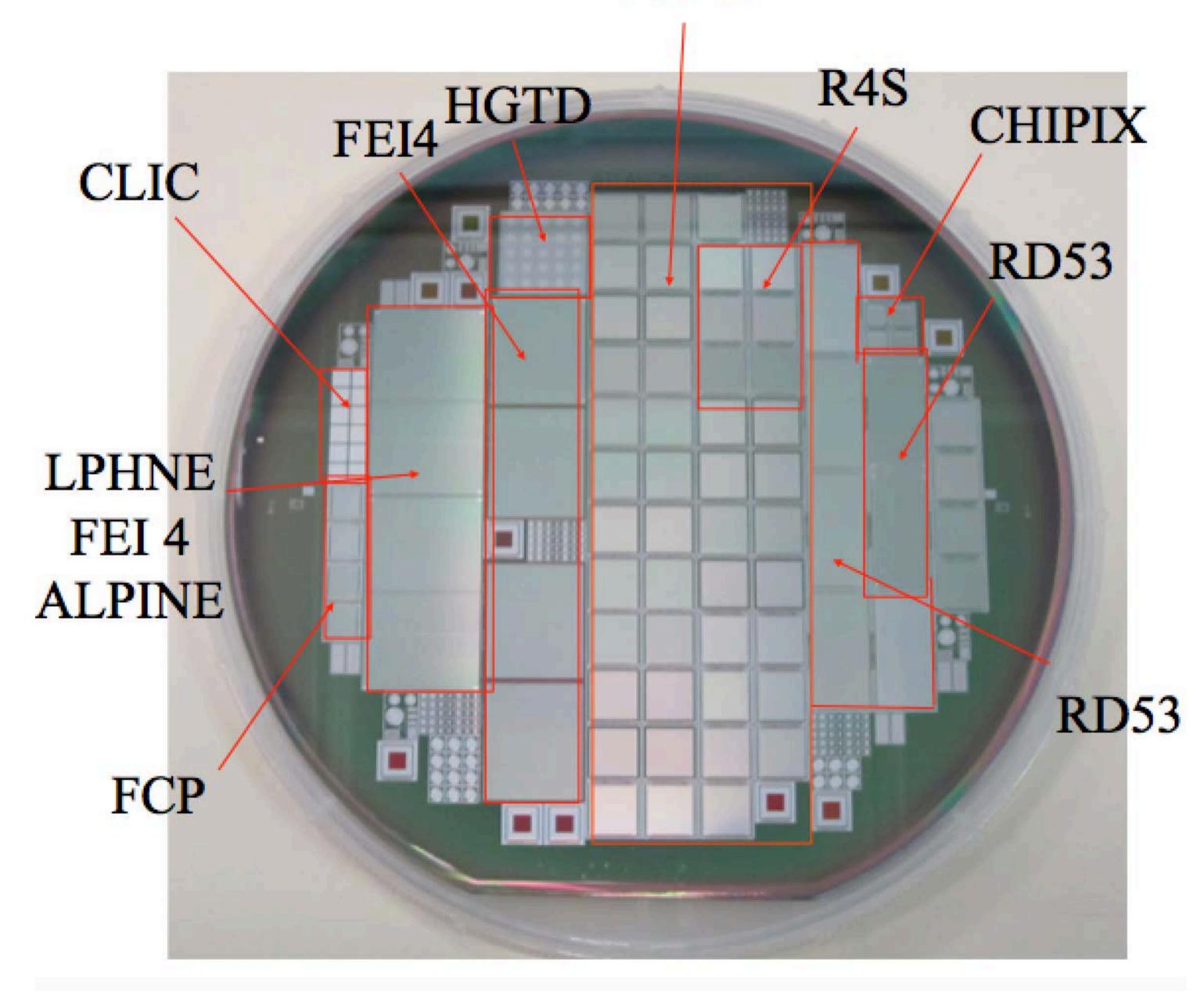
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Recent LPNHE planar pixel productions with FBK

Active edge sensor production (2018)



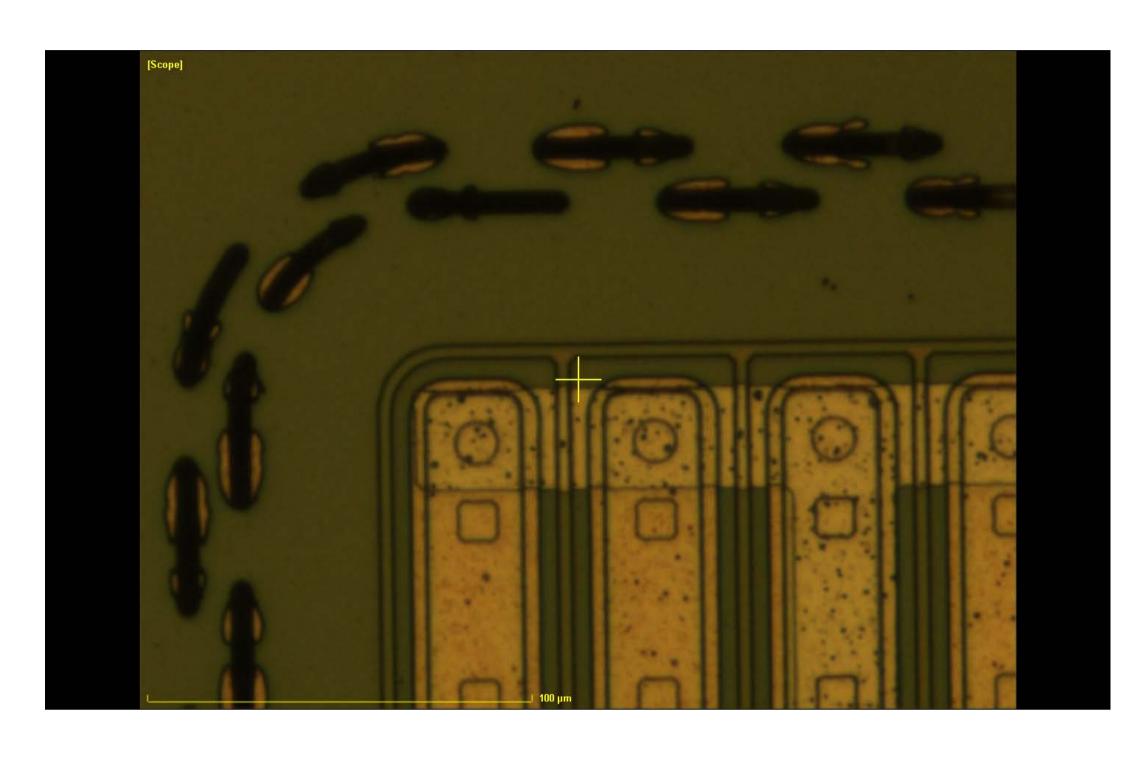




- Staggered trench, doped with BBr₃ gas source and filled with poly
- Pixel-to-edge down to 50 μm
- RD53a compatible sensors + many other designs
- In the RD53 part: two pixel geometries, 50x50 and $25x100 \mu m^2$
- Different biasing schemes:
 - Temporary Metal
 - Punch through (with different designs)



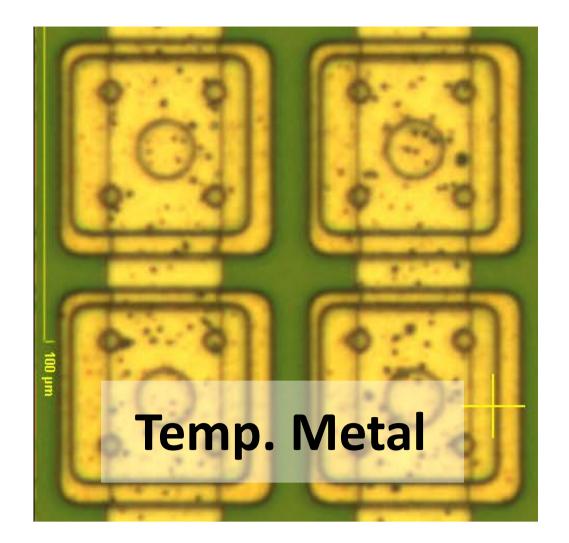


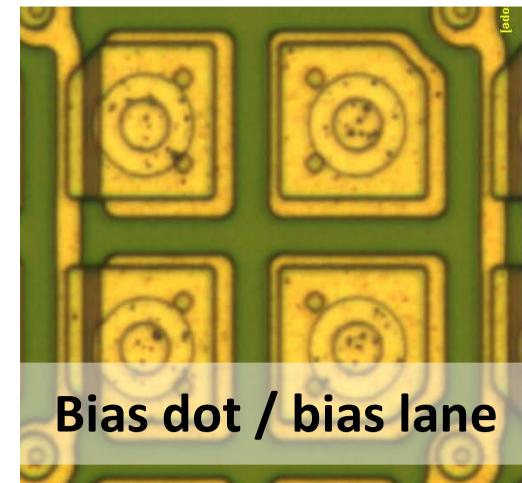






Sensors with different bias networks

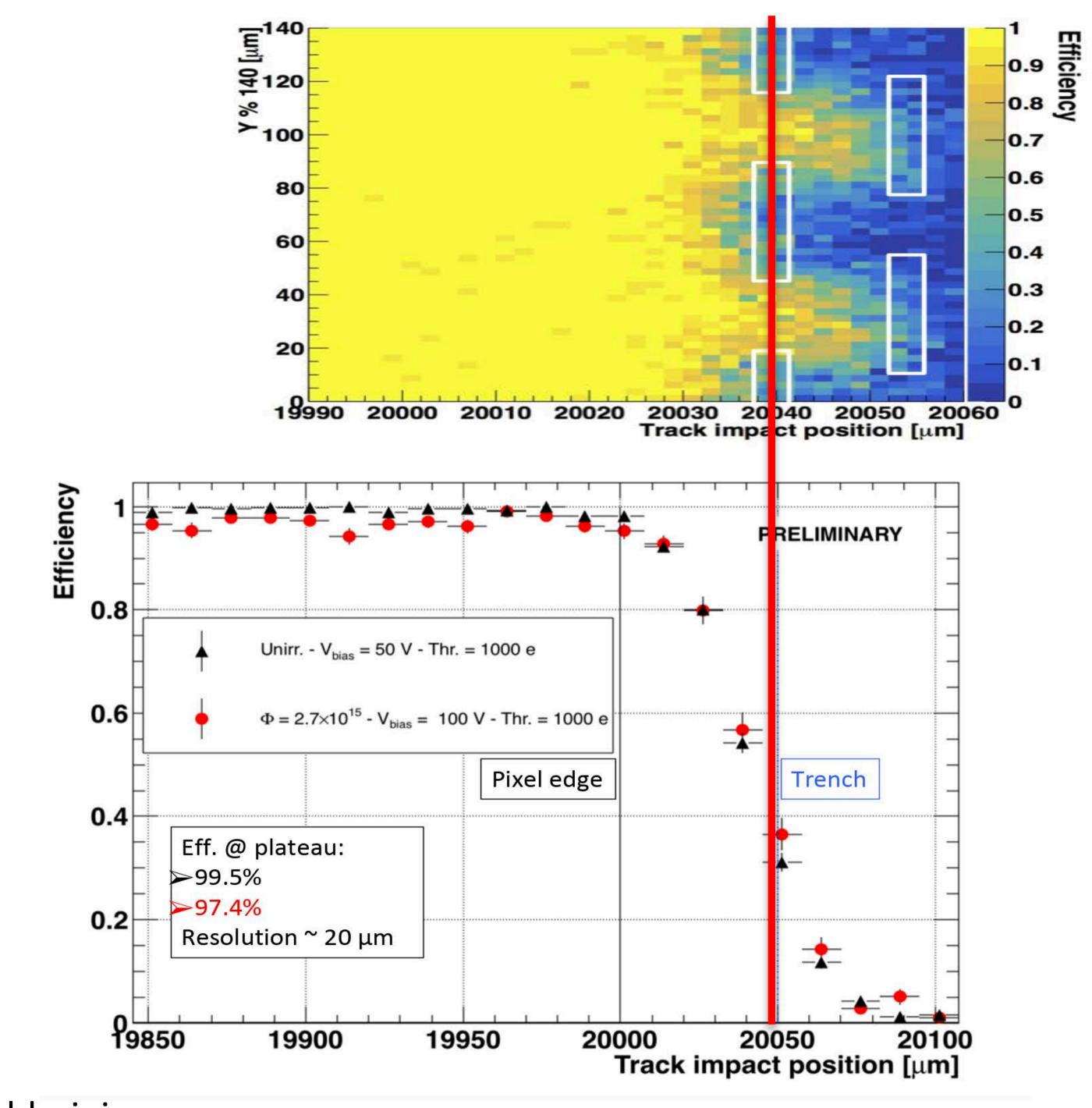




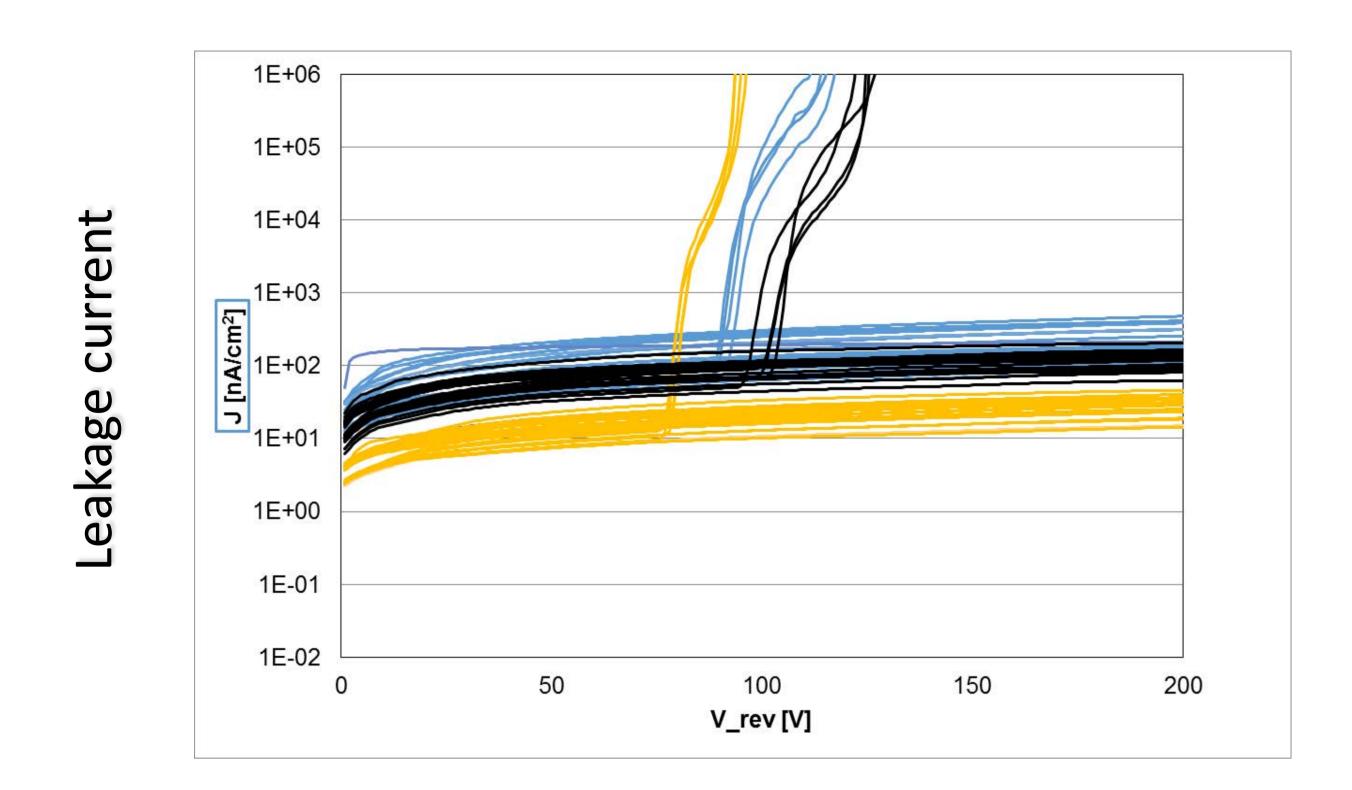
Temporary Metal Punch-Trough

- Straight
- Wiggled

Significant hit efficiency even in proximity of the trench edge: >50% at $10\mu m$ distance



Breakdown typically larger than 200V

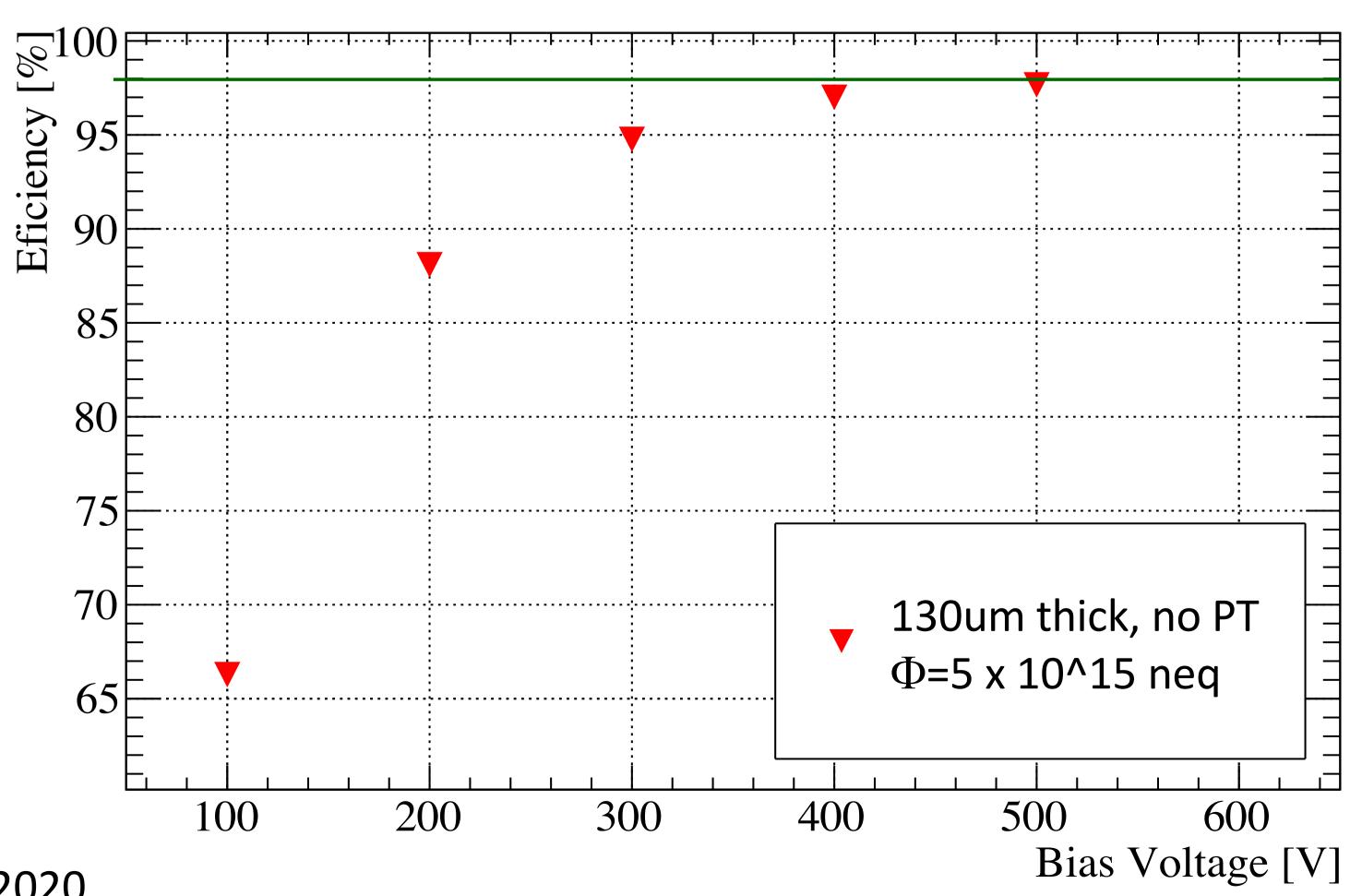


Very aggressive design:

0-1-2 guard rings (0-1 for active edge)

Distance from pixel to trench: $60 \text{ to } 80 \mu \text{m}$

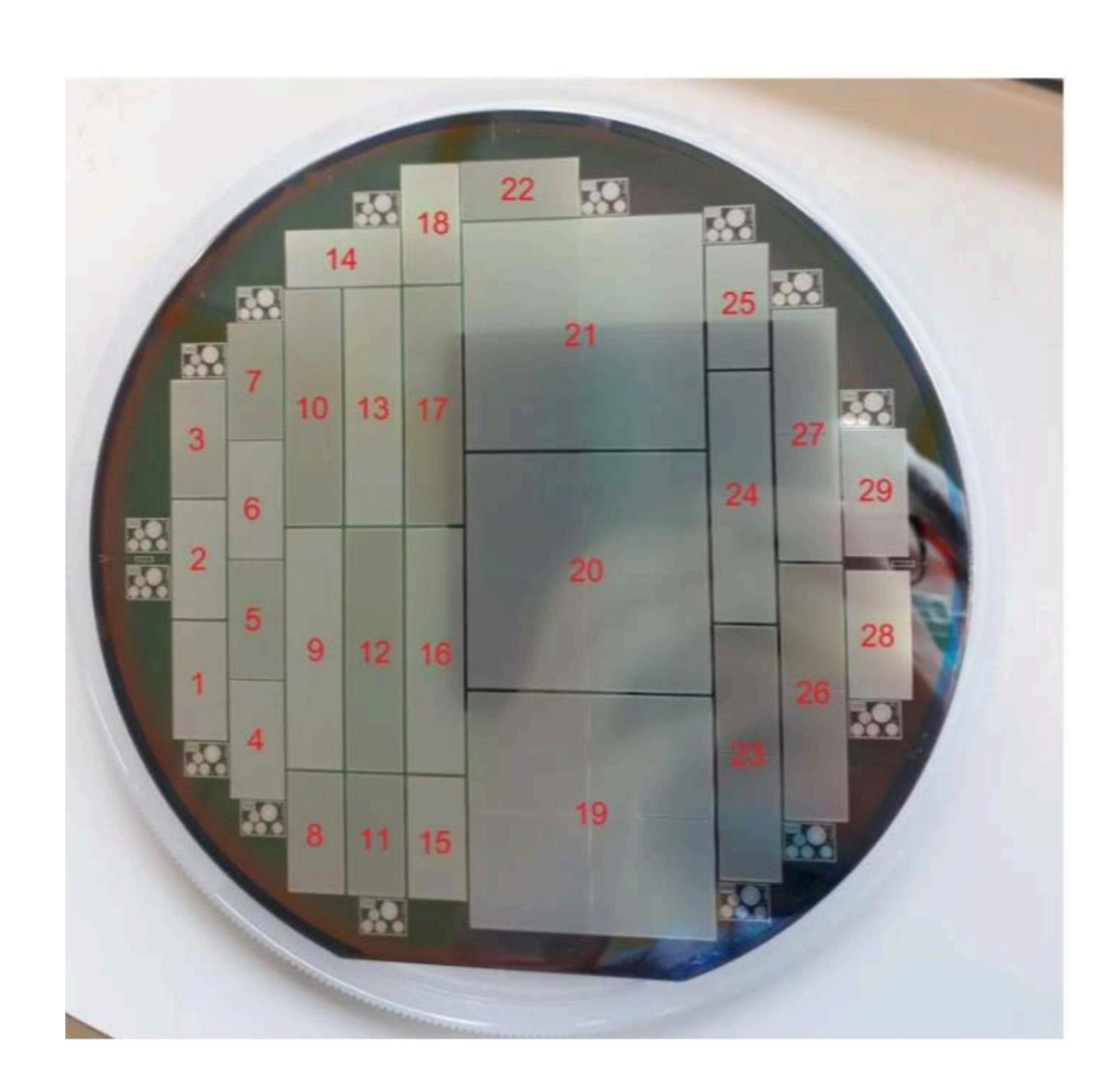
Characterization at test-beams after irradiation Hit-efficiency well above 97%



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Standard edge (2019) – ATLAS Inner Tracker (ITk) oriented



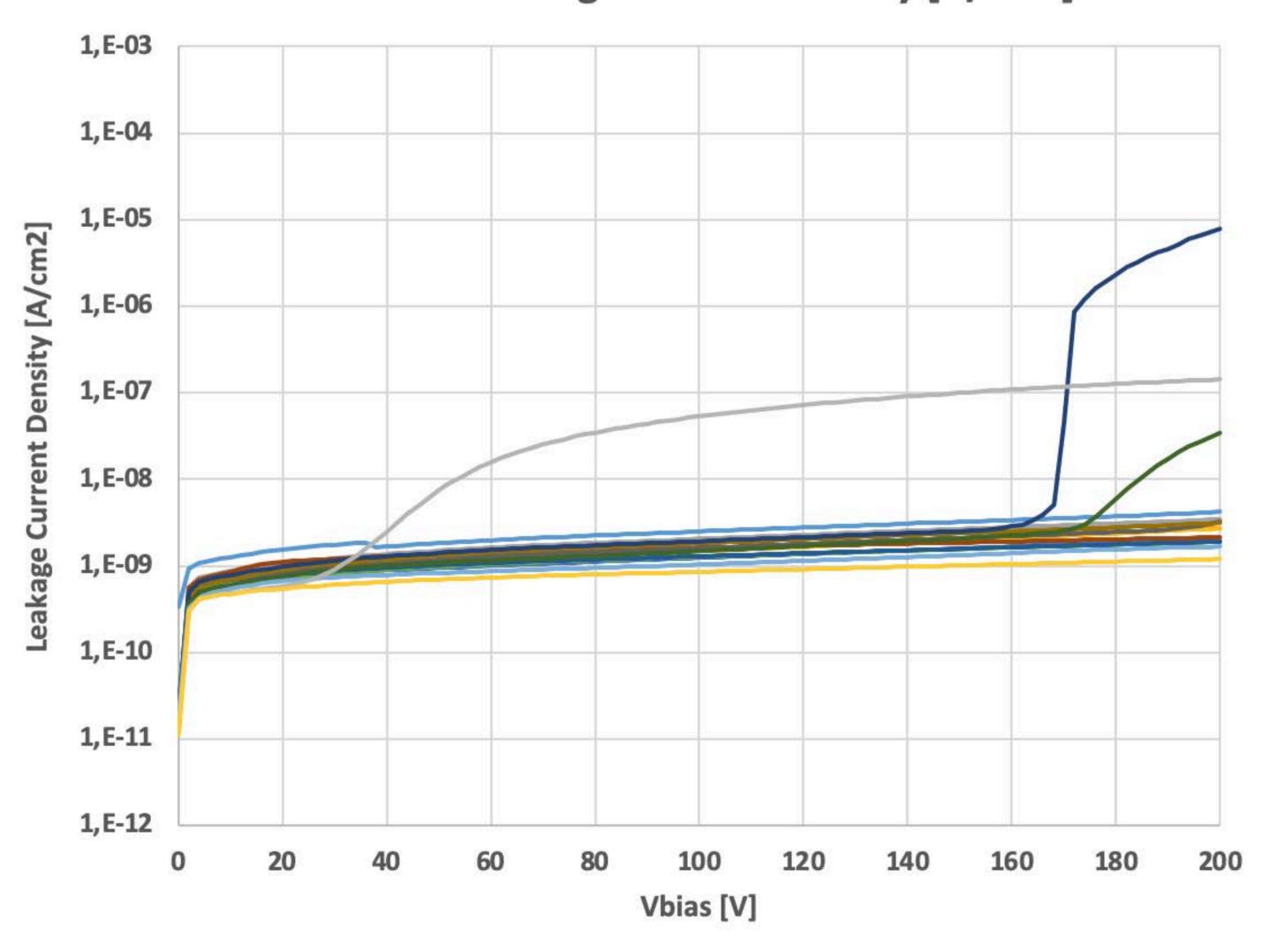
6" 50-100-150 μm thick n-on-p sensors (no active edge)

- Single RD53a sensors, Double RD53a,
 Quad ITk sensors
- Different biasing schemes:
 - Temporary Metal
 - Punch through (with different designs)

Good electrical properties

- Breakdown voltage before irradiation typically larger than 200V
- Guard-ring regions of 250 and 450 μm
- Depletion voltage in the 10-15V (for 100μm) and 20-30V range (for 150 μm)

Device SINGLE - Leakage Current Density [A/cm2]



Characterisation of 100/150 µm thick sensors

Tested at DESY after irradiation

- 2 x 10¹5
- 5 x 10¹5

Lack of time has prevented to apply parylene protection for HV

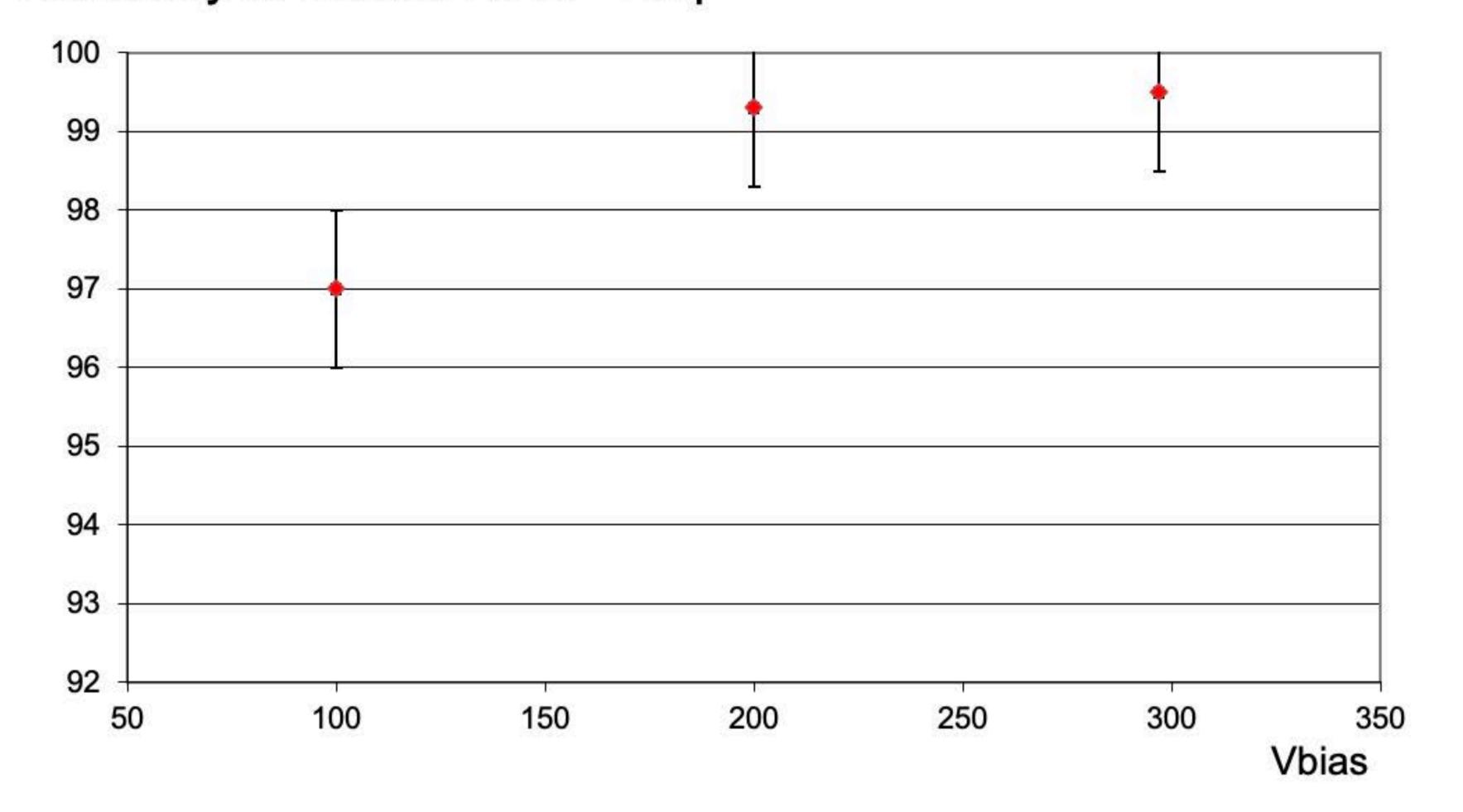
HV limited to 400V after irradiation

During the runs at 5x10¹⁵ neq a cooling problem had a large impact on the leakage current of all the tested modules The effective Vbias was significantly different from the provided tension due to some voltage drop in resistances

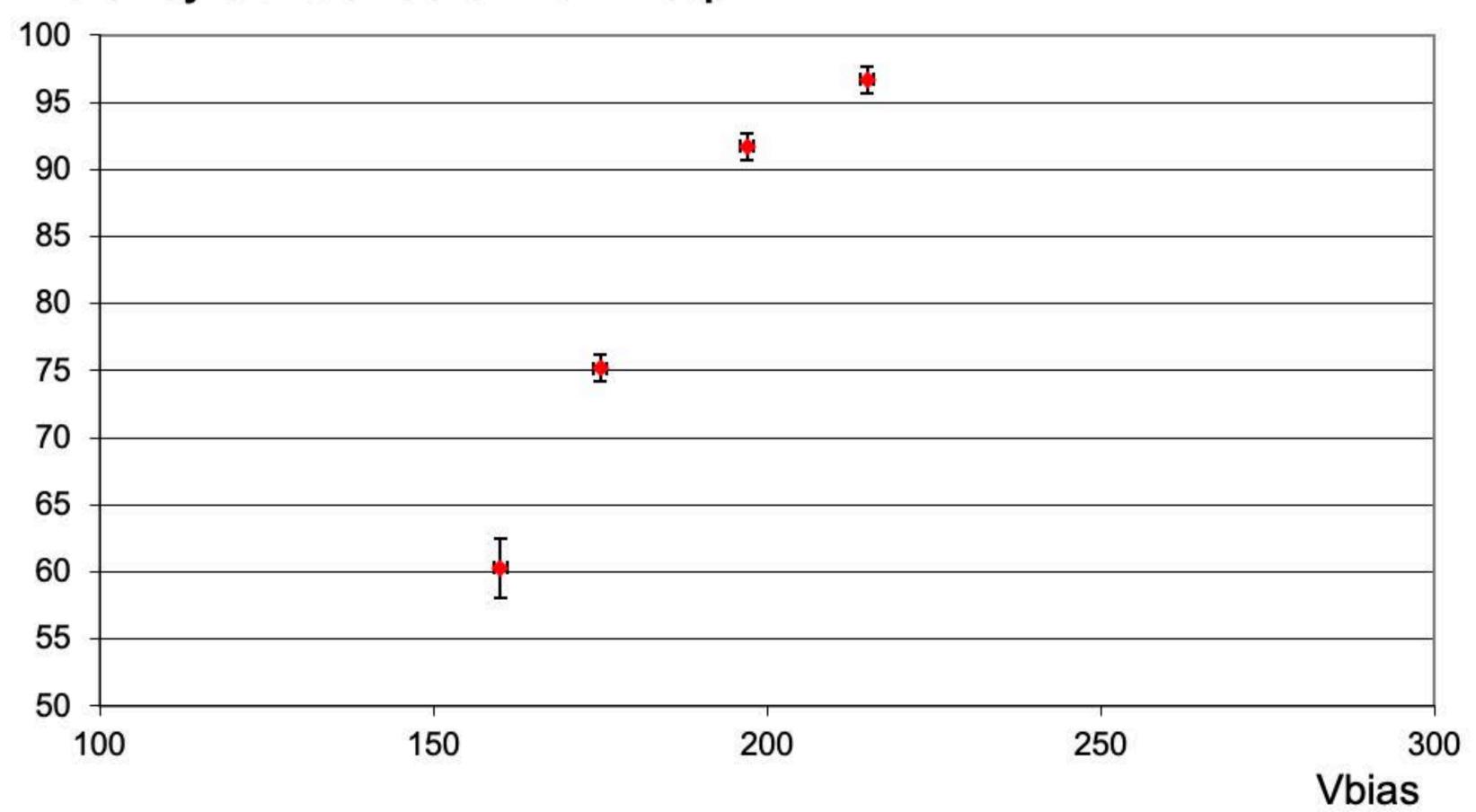
The effective Vbias has been carefully evaluated

Even at a fluence of 5x10¹⁵ neq, the hit efficiency reaches a value well above 97% (the ITk standard for that dose) already at (effective) Vbias < 250V

Efficiency at fluence 2x10¹⁵ neq



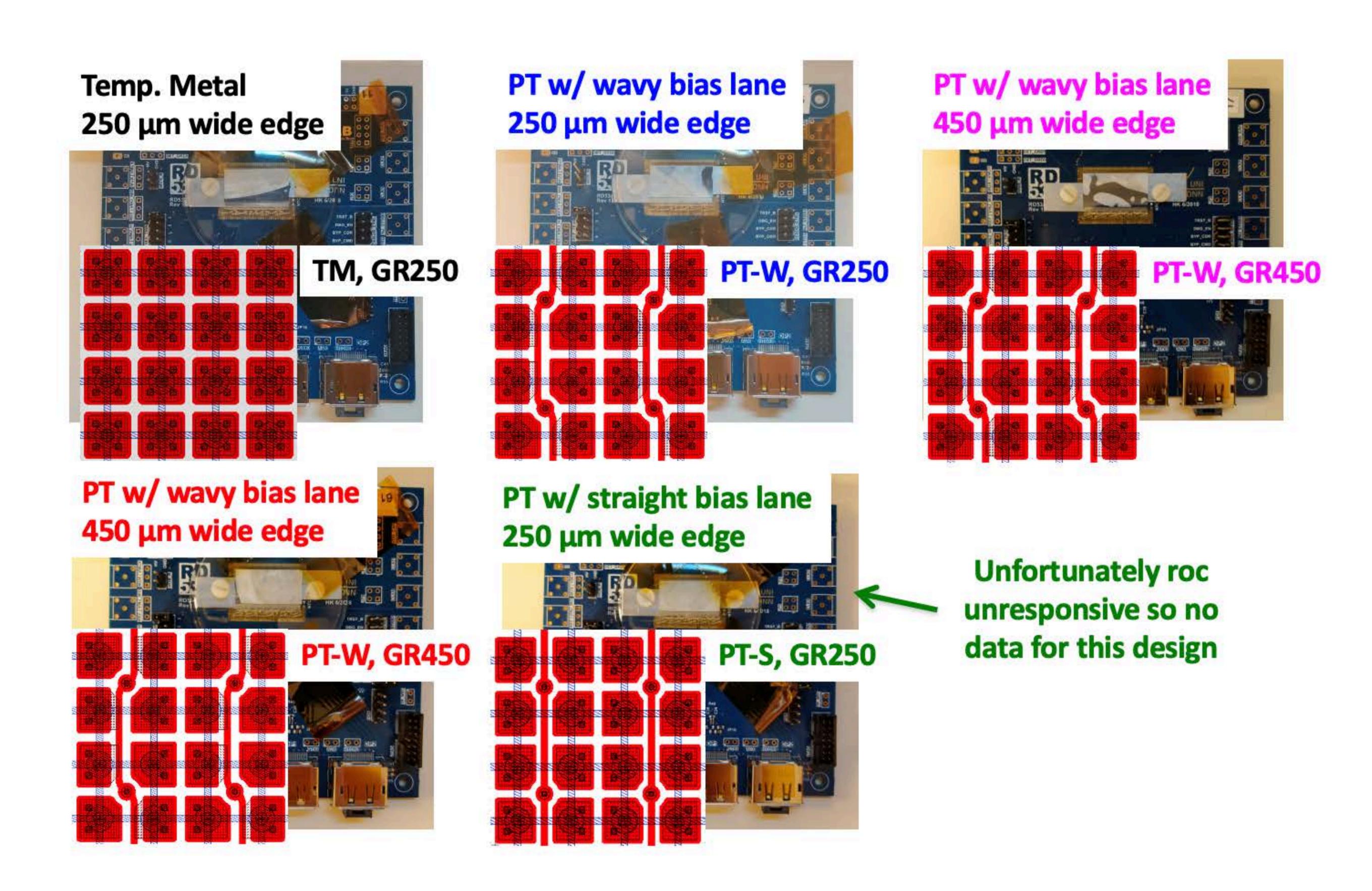
Efficiency at fluence 5x10¹⁵ neq



Characterisation of 50 µm thick sensors

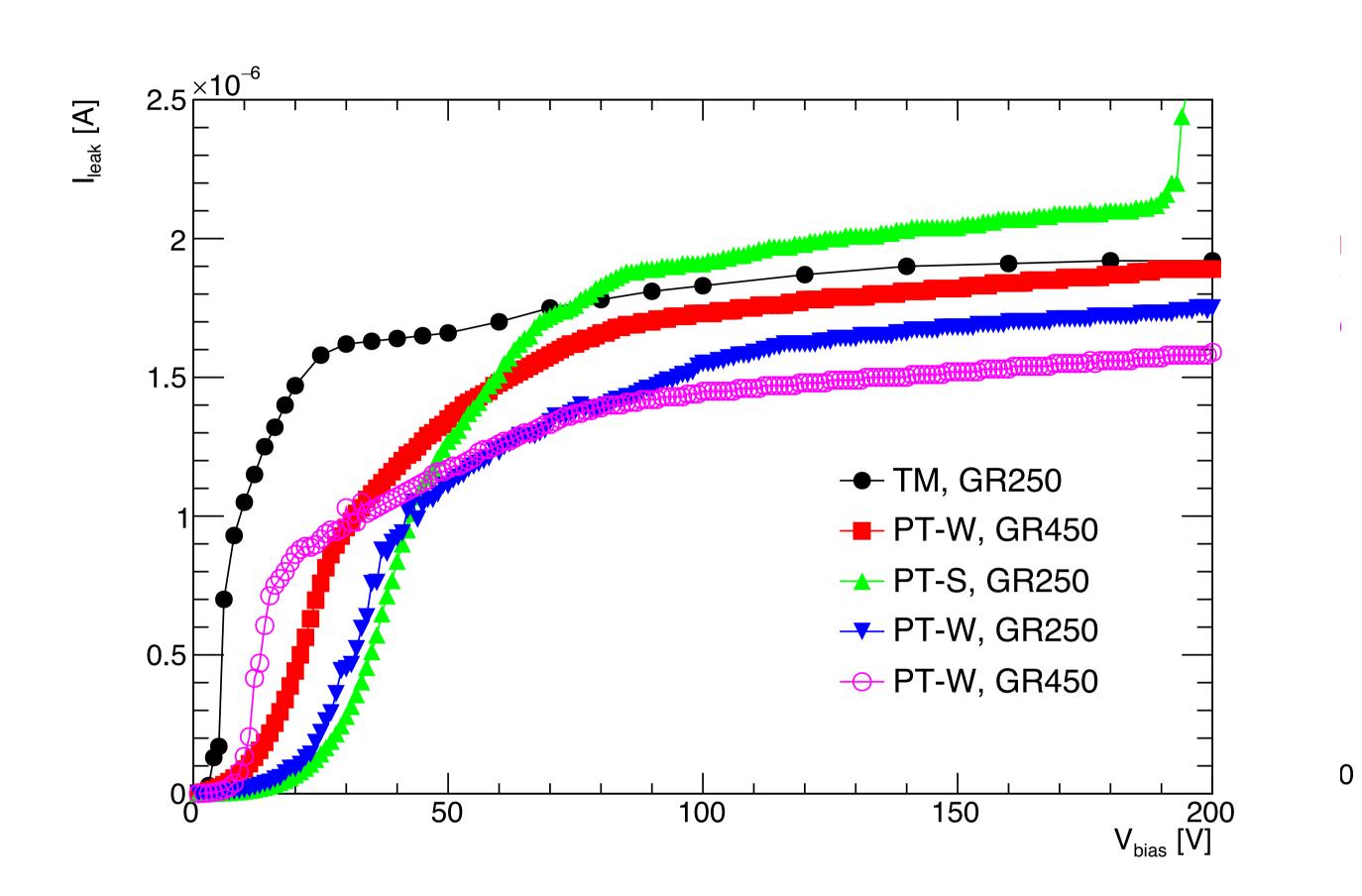
The lower threshold achievable with the RD53A FE chip allowed to design and produce thinner sensors

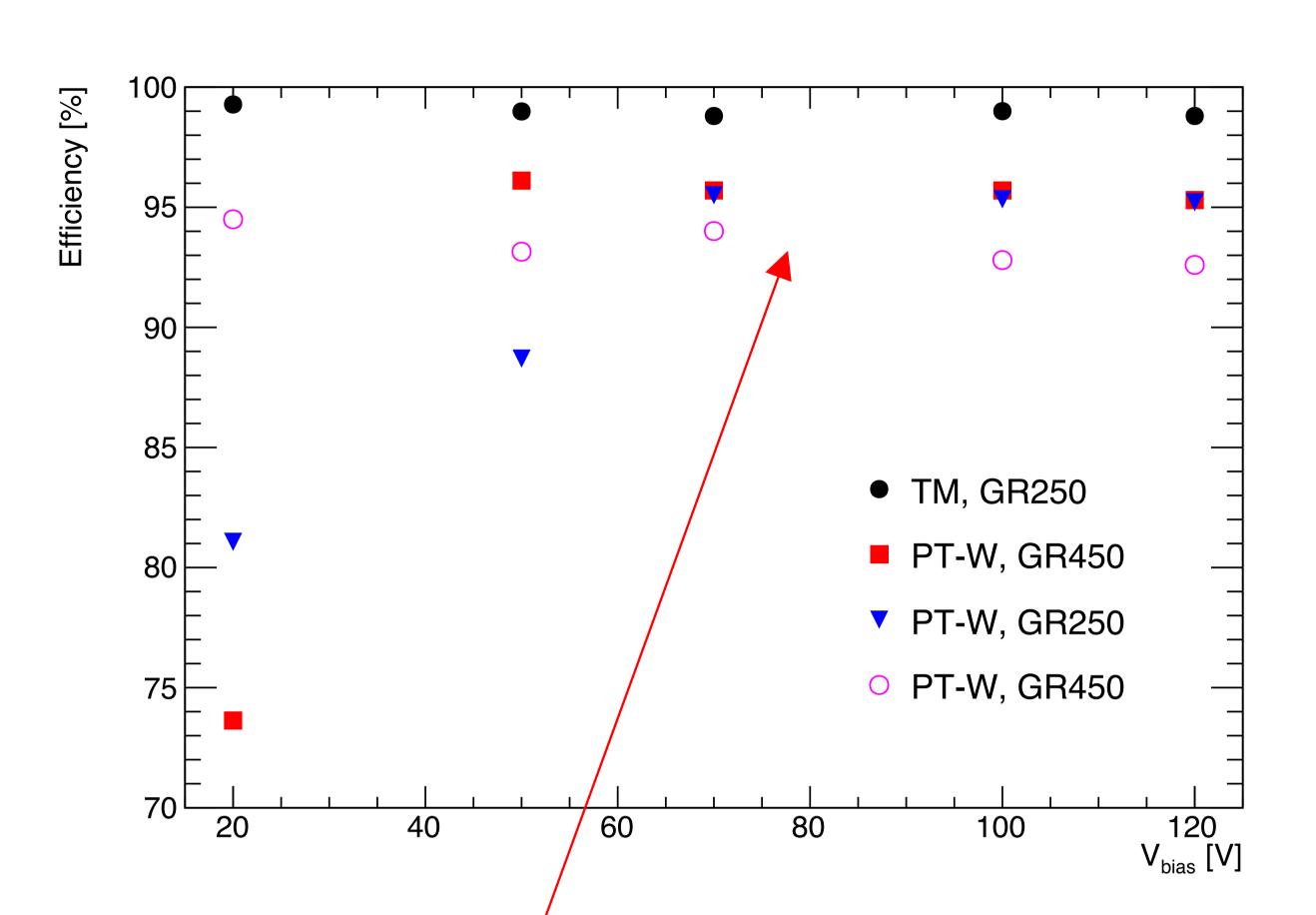
Five modules of $50\mu m$ thickness with different bias network structure and guard ring region were tested on beam and have been now irradiated. Unfortunately one is not working, data available from the remaining four



Characterisation of 50 µm thick sensors

Typical depletion voltage of the order of 20V with a couple of sensors at 40V (rather high values, reason for this still under investigation)

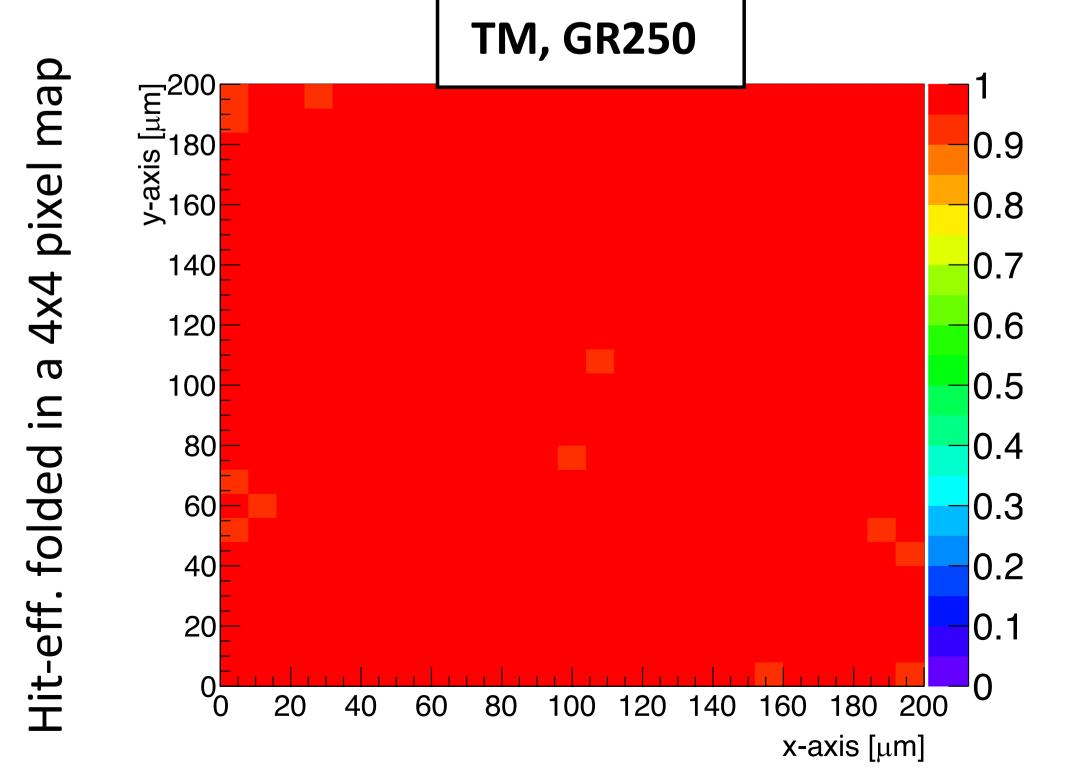


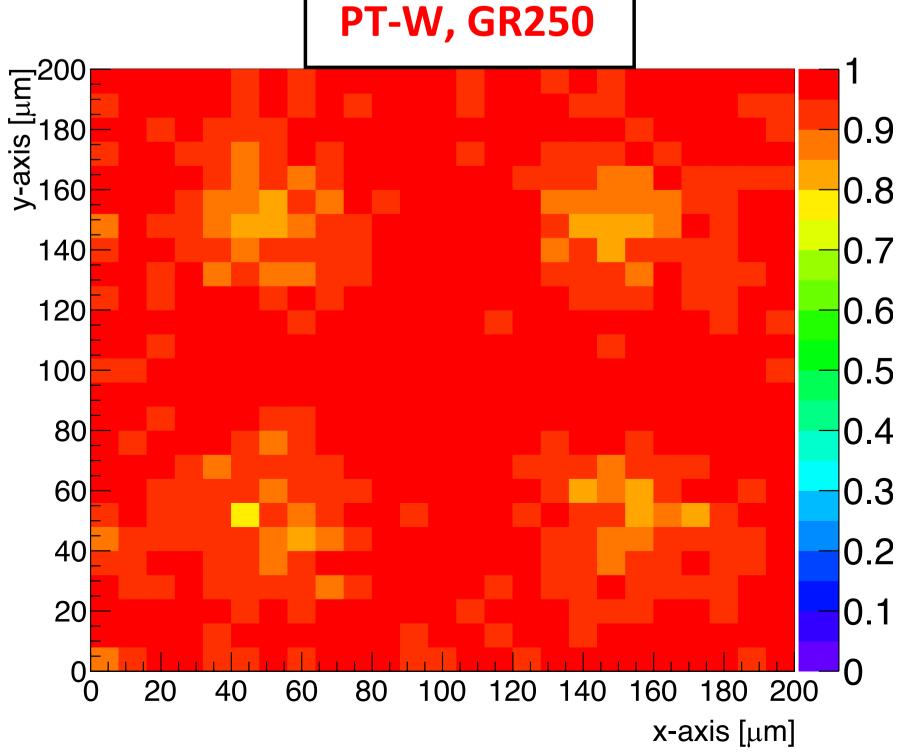


Effect of PT biasing network more evident wrt 100/150 μm (for tracks at normal angle)

Efficiency for Temporary Metal is stable around 99% even at very low bias voltage

Devices with PT networks lose a few % due to the inefficient regions of the bias dots / lines





Sensors have been irradiated up to $5x10^{15}$ neq but test-beam characterization has not been possible yet due to COVID.

That will happen soon, stay tuned